

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claims 1-2, 5 and 12-16 as follows:

LISTING OF CLAIMS:

1. (Currently Amended) A test socket for testing electrical characteristics of a semiconductor device by connecting probes, arranged in a grid-like form, with outer connecting terminals of the semiconductor device, arranged in a grid-like form, and electrically connecting the probes with the outer connecting terminals comprising:

a connecting sheet, made of an electrically elastically deformative insulating material, and having electrodes for electrically connecting the probes to the outer connecting terminals of the semiconductor device wherein a plurality of protrusions, formed into a smooth curved surface, and a plurality of recesses, formed into a smooth curved surface and extending in the vicinity of the protrusions, are formed in the electrodes of the connecting sheet, being in contact with the outer connecting terminals of the semiconductor device.

2. (Currently Amended) The test socket according to claim 1, wherein the electrodes of the connecting sheet are electrodes being in contact with probes, and electrodes being in contact with the outer connecting terminals of the semiconductor device, and

the electrodes include two different types of the electrodes which are connected through electrically connecting holes, formed in the elastically deformative

insulating member and located on a front surface and a back surface of the connecting sheet.

3. (Original) The test socket according to claim 1,
wherein a shape of tips of the probes, being in contact with the electrodes of the connecting sheet, is like a recess or a protrusion, and
the electrodes are shaped like a protrusion, which can be engage with the probes of the recess-like shape or a recess, which can be engaged with the probes of the protrusion-like shape.

4. (Original) A test socket having a circuit board, which transmits an electrical signal for testing electrical characteristics of a semiconductor device to outer connecting terminals of the semiconductor device, arranged in a grid-like form, and receives the electrical signal from the outer connecting terminals, and transmits the electrical signal to a testing equipment and receives the electrical signal from the testing equipment, comprising:

a connecting sheet, made of an elastically deformative insulating member and having electrodes for electrically connecting the circuit board with the outer connecting terminals of the semiconductor device wherein a plurality of protrusions, formed into a smooth curved surface, and a plurality of recesses, formed into a smooth curved surface and extending in the vicinity of the protrusions, are formed in the electrodes of the connecting sheet, being in contact with the outer connecting terminals of the semiconductor device.

5. (Currently Amended) The test socket according to claim 4,
wherein the electrodes of the connecting sheet are electrodes, being in
contact with the circuit board, and electrodes, being in contact with the outer
connecting terminals of the semiconductor device,

the electrodes include two different types of the electrodes which are
connected through electrically connecting holes, formed in the elastically deformative
insulating member, and connecting wires, and are located on a front surface and a
back surface of the connecting sheet, and

a distance between the electrodes, being in contact with the circuit board, and
a distance between the electrodes, being in contact with the outer connecting
terminals of the semiconductor device, are different.

6. (Original) The test socket according to claim 1, further comprising:
a guiding member having holes at positions corresponding to the outer
connecting terminals of the semiconductor device and overlapping the connecting
sheet.

7. (Original) The test socket according to claim 4, further comprising:
a guiding member having holes at positions corresponding to the outer
connecting terminals of the semiconductor device and overlapping the connecting
sheet.

8. (Original) The test socket according to claim 1,
wherein the electrodes of the connecting sheet, being in contact with the outer
connecting terminals of the semiconductor device, have a spaced portion and a
bending portion, and

the bending portion is in contact with the outer connecting terminal of the
semiconductor device.

9. (Original) The test socket according to claim 4,
wherein the electrodes of the connecting sheet, being in contact with the outer
connecting terminals of the semiconductor device, have a spaced portion and a
bending portion, and

the bending portion is in contact with the outer connecting terminal of the
semiconductor device.

10. (Original) The test socket according to claim 1,
wherein a through hole is formed in a part of the connecting sheet.

11. (Original) The test socket according to claim 4,
wherein a through hole is formed in a part of the connecting sheet.

12. (Currently Amended) [[The]] A connecting sheet included in a [[the]]
~~test socket according to claim 1 for testing electrical characteristics of a~~
~~semiconductor device by connecting probes, arranged in a grid-like form, with outer~~
~~connecting terminals of the semiconductor device, arranged in a grid-like form, and~~

electrically connecting the probes with the outer connecting terminals, the connecting sheet comprising:

an elastically deformative insulating material, and having electrodes for electrically connecting the probes to the outer connecting terminals of the semiconductor device wherein a plurality of protrusions, formed into a smooth curved surface, and a plurality of recesses, formed into a smooth curved surface and extending in the vicinity of the protrusions, are formed in the electrodes of the connecting sheet, being in contact with the outer connecting terminals of the semiconductor device.

13. (Currently Amended) The connecting sheet included in the test socket according to claim [[2]] 12,

wherein the electrodes of the connecting sheet are electrodes being in contact with probes, and electrodes being in contact with the outer connecting terminals of the semiconductor device, and

the electrodes include two different types of electrodes which are connected through electrically connecting holes, formed in the elastically deformative insulating member and located on a front surface and a back surface of the connecting sheet.

14. (Currently Amended) The connecting sheet included in the test socket according to claim [[3]] 12,

wherein a shape of tips of the probes, being in contact with the electrodes of the connecting sheet, is like a recess or a protrusion, and

the electrodes are shaped like a protrusion, which can be engage with the probes of the recess-like shape or a recess, which can be engaged with the probes of the protrusion-like shape.

15. (Currently Amended) [[The]] A connecting sheet included in [[the]] a test socket according to claim [[4]] having a circuit board, which transmits an electrical signal for testing electrical characteristics of a semiconductor device to outer connecting terminals of the semiconductor device, arranged in a grid-like form, and receives the electrical signal from the outer connecting terminals, and transmits the electrical signal to a testing equipment and receives the electrical signal from the testing equipment, the connecting sheet comprising:

an elastically deformative insulating member and having electrodes for electrically connecting the circuit board with the outer connecting terminals of the semiconductor device wherein a plurality of protrusions, formed into a smooth curved surface, and a plurality of recesses, formed into a smooth curved surface and extending in the vicinity of the protrusions, are formed in the electrodes of the connecting sheet, being in contact with the outer connecting terminals of the semiconductor device.

16. (Currently Amended) The connecting sheet included in the test socket according to claim [[5]] 15,

wherein the electrodes of the connecting sheet are electrodes, being in contact with the circuit board, and electrodes, being in contact with the outer connecting terminals of the semiconductor device,

the electrodes include two different types of electrodes which are connected through electrically connecting holes, formed in the elastically deformative insulating member, and connecting wires, and are located on a front surface and a back surface of the connecting sheet, and

a distance between the electrodes, being in contact with the circuit board, and a distance between the electrodes, being in contact with the outer connecting terminals of the semiconductor device, are different.